- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

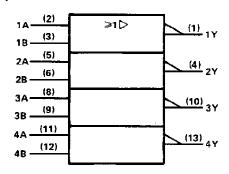
These devices contain four independent 2-input-NOR line drivers. They perform the Boolean function $Y = \overline{A} + \overline{B}$ or $Y = \overline{A} \cdot \overline{B}$. The SN54128 is designed to drive 75 ohm lines. The SN74128 is designed to drive 50 ohm lines.

The SN54128 is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN74128 is characterized for operation from 0 $^{\circ}\text{C}$ to 70 $^{\circ}\text{C}$.

logic diagram (each driver)



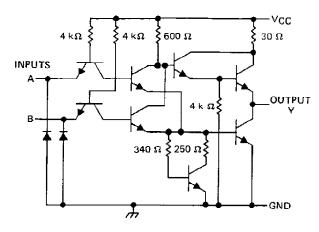
logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54128 . . . J OR W PACKAGE **SN74128...N PACKAGE** (TOP VIEW) 17 □1 / 14口 Vcc 13 4Y 1A 🛮 2 18 □3 12 4B 2Y **□**4 11 4A 2A 🗆 5 10 3Y 28 □ 6 9 3B GND ☐ 7 8 3A

schematic (each driver)



Resistor values shown are nominal,

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Operating free-air temperature range:	SN54'	- 55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54128, SN74128 LINE DRIVERS

recommended operating conditions

		L	SN5412	В				
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4,5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2		-	2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			- 29			- 42.4	mA
loL	Low-level output current			48			48	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	ş t	MIN	TYP‡	MAX	UNIT
ViK	V _{CC} = MIN, I _I = -12 mA				1.5	V
	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH}	= - 2.4 mA	2.4	3,4		
v_{OH}	V _{CC} = MIN, V _{IL} = 0.4 V, I _{OH} = -13.2 mA		2.4			V
	$V_{CC} = MIN$, $V_{IL} = 0.4 \text{ V}$, $I_{OH} = 0.4 \text{ V}$	= MAX	2			1
VOL	VCC = MIN, VIH = 2 V, IOL	≈ 4B mA		0.26	0.4	V
łį	V _{CC} = MAX. V ₁ = 5.5 V				1	mΑ
l _{IH}	V _{CC} = MAX, V _I = 2.4 V				40	μА
<u> </u>	V _{CC} = MAX, V ₁ = 0.4 V				- 1.6	mA
los§	V _{CC} = MAX		-70		180	mA
1ссн	VCC = MAX			12	21	mA
ICCL	V _{CC} = MAX			33	57	mΑ

t For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN	TYP	MAX	UNIT	
tPLH			D -122.5			6	9	ns
[₹] PHL	A or B	V	R _L = 133 Ω,	C _L ≈ 50 pF		8	12	∩s
₹PLH .	70,0	,	$R_1 = 133 \Omega$,	C = 150 = 5		10	15	ns
^t PHL			HE - 133 38,	C _L = 150 pF		12	18	П5

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

 $[\]pm$ All typical values are at VCC = 5 V, TA = 25°C. \S Not more than one output should be shorted at a time.

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1-May-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9861101QCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9861101QC A SNJ54128J
5962-9861101QDA	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9861101QD A SNJ54128W
5962-9861101QDA	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9861101QD A SNJ54128W
SN54128J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54128J
SN54128J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54128J
SN74128D	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74128
SN74128D	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74128
SN74128N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74128N
SN74128N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74128N
SN74128NSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN74128
SN74128NSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN74128
SNJ54128J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9861101QC A SNJ54128J
SNJ54128J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9861101QC A SNJ54128J
SNJ54128W	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9861101QD A SNJ54128W
SNJ54128W	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9861101QD A SNJ54128W

⁽¹⁾ Status: For more details on status, see our product life cycle.

PACKAGE OPTION ADDENDUM

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(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54128, SN74128:

Catalog: SN74128

Military: SN54128

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

0.1. ---

PACKAGE MATERIALS INFORMATION

www.ti.com 7-Dec-2024

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74128NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 7-Dec-2024



*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74128NSR	SOP	NS	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 7-Dec-2024

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9861101QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74128D	D	SOIC	14	50	506.6	8	3940	4.32
SN74128N	N	PDIP	14	25	506	13.97	11230	4.32
SN74128N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54128W	W	CFP	14	25	506.98	26.16	6220	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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